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2SA836

Silicon PNP Epitaxial

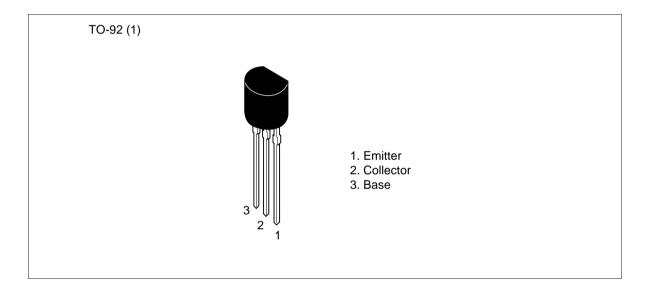


ADE-208-316 (Z) 1st. Edition Mar. 2001

Application

Low frequency low noise amplifier

Outline



2SA836

Absolute Maximum Ratings (Ta = 25°C)

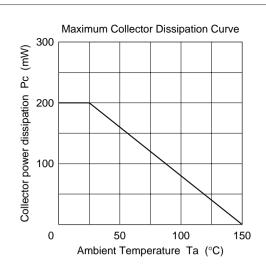
Symbol	Ratings	Unit
V _{CBO}	– 55	V
V_{CEO}	-55	V
V_{EBO}	– 5	V
I _c	-100	mA
I _E	100	mA
P _c	200	mW
Tj	150	°C
Tstg	-55 to +150	°C
	V_{CBO} V_{CEO} V_{EBO} I_{C} I_{E} P_{C}	V_{CBO} —55 V_{CEO} —55 V_{EBO} —5 I_{C} —100 I_{E} 100 P_{C} 200 Tj 150

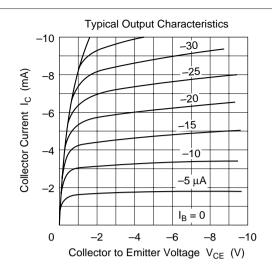
Electrical Characteristics ($Ta = 25^{\circ}C$)

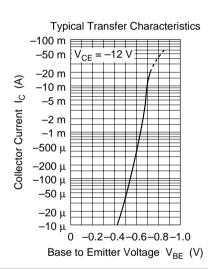
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	- 55	_	_	V	$I_{c} = -10 \ \mu A, \ I_{e} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	- 55	_	_	V	$I_{C} = -1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	- 5	_	_	V	$I_{E} = -10 \ \mu A, \ I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	-100	nA	$V_{CB} = -18 \text{ V}, I_{E} = 0$
Emitter cutoff current	I _{EBO}	_	_	-50	nA	$V_{EB} = -2 \text{ V}, I_{C} = 0$
DC current transfer ratio	h _{FE} *1	160	_	500		$V_{CE} = -12 \text{ V}, I_{C} = -2 \text{ mA}$
Collector to emitter saturation voltage	$V_{\text{CE}(\text{sat})}$	_	-0.1	-0.5	V	$I_{\rm C} = -10 \text{ mA}, I_{\rm B} = -1 \text{ mA}$
Base to emitter voltage	V_{BE}	_	-0.66	-0.75	V	$V_{CE} = -12 \text{ V}, I_{C} = -2 \text{ mA}$
Gain bandwidth product	f _T	_	200	_	MHz	$V_{CE} = -12 \text{ V}, I_{E} = -2 \text{ mA}$
Collector output capacitance	Cob	_	2.0	_	pF	$V_{CB} = -10 \text{ V}, I_{E} = 0, f = 1 \text{MHz}$
Noise figuer	NF	_	1	5	dB	$V_{CE} = -6 \text{ V}, \qquad f = 10 \text{ Hz}$
		_	0.5	1	dB	$I_{c} = -0.1 \text{mA},$ $f = 1 \text{ kHz}$ $R_{g} = 10 \text{ k}\Omega$

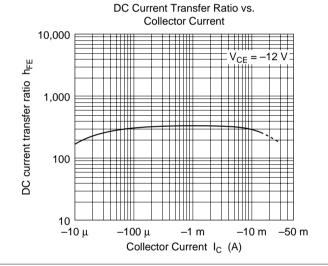
Note: 1. The 2SA836 is grouped by $h_{\rm FE}$ as follows.

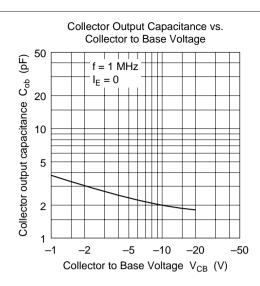
С	D
160 to 320	250 to 500

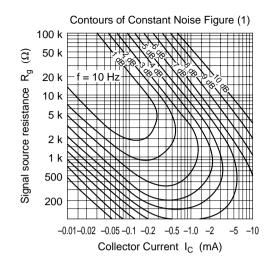


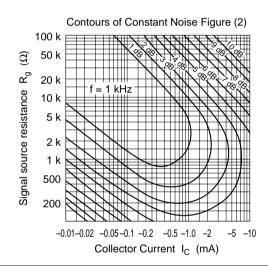




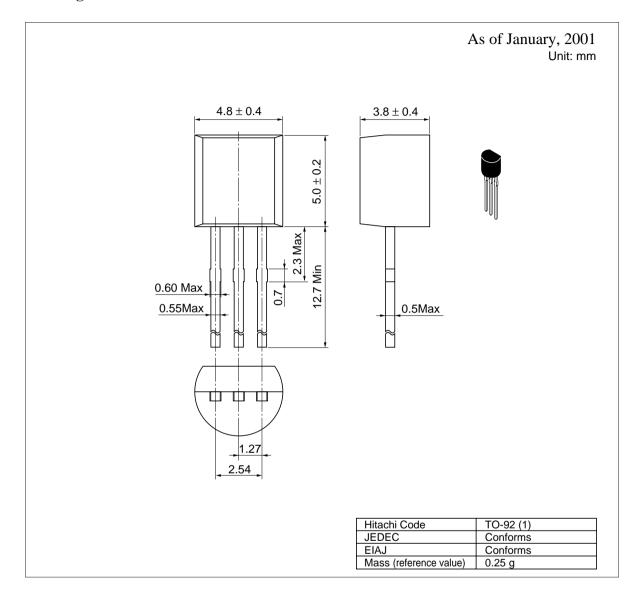








Package Dimensions



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